

FIG. 1

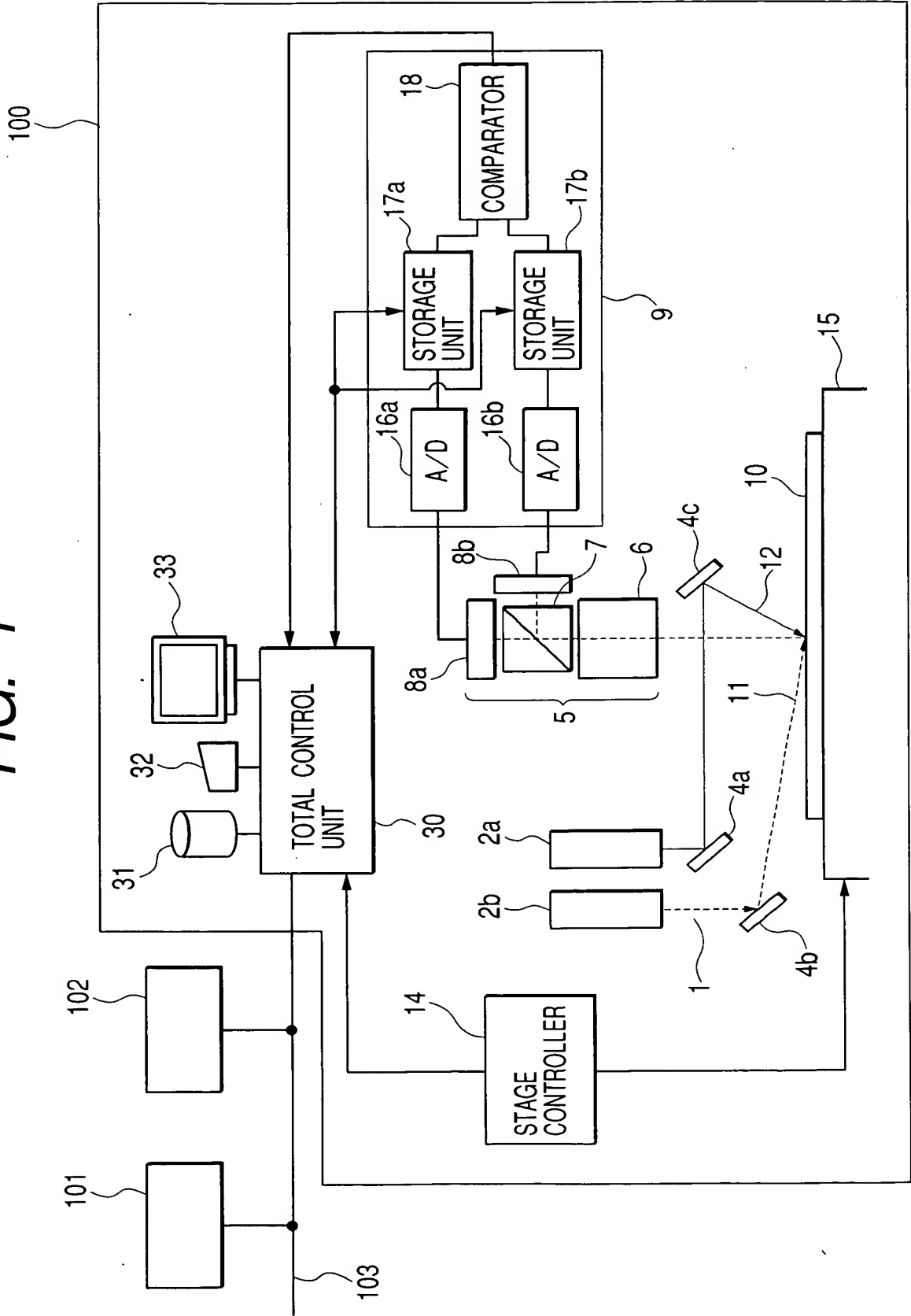


FIG. 2(a)

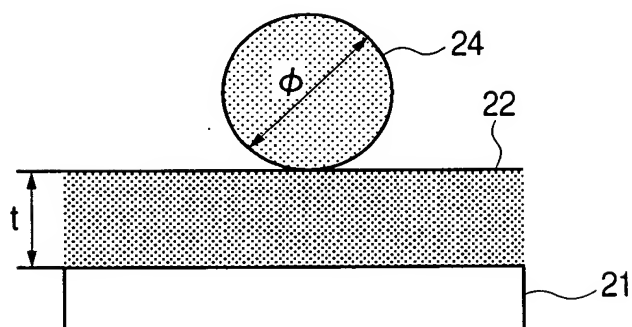


FIG. 2(b)

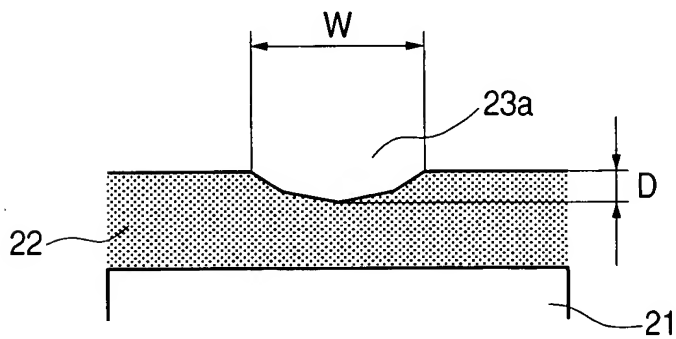


FIG. 3(a)

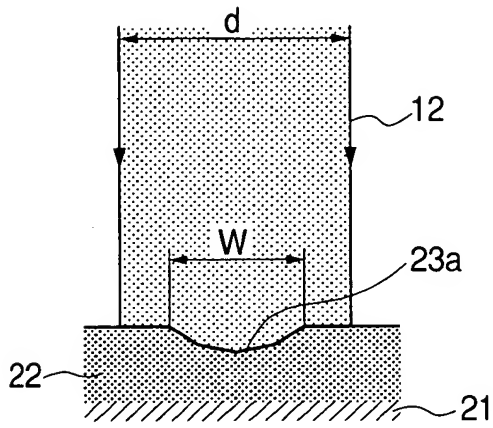


FIG. 3(b)

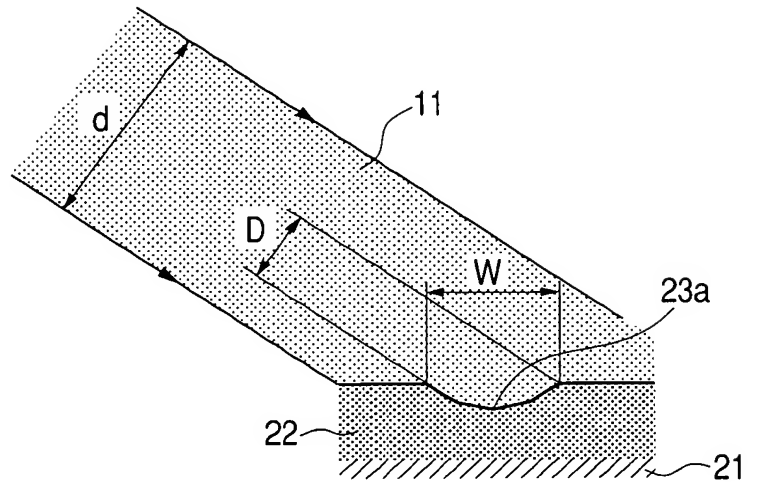


FIG. 3(c)

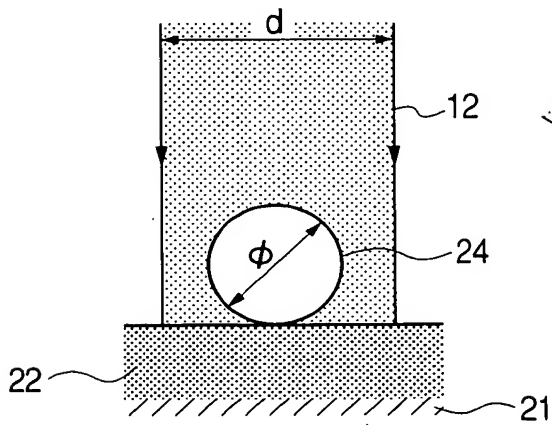


FIG. 3(d)

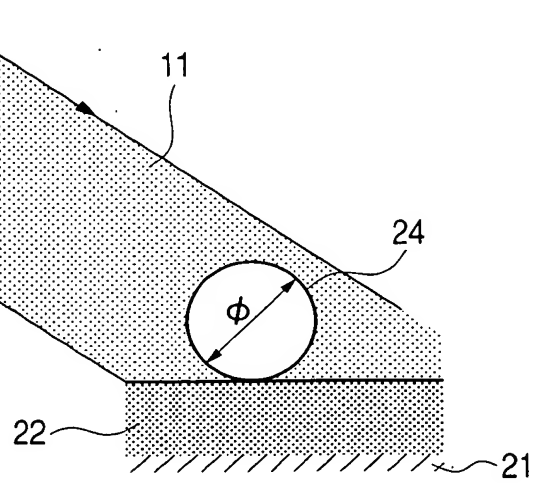


FIG. 4

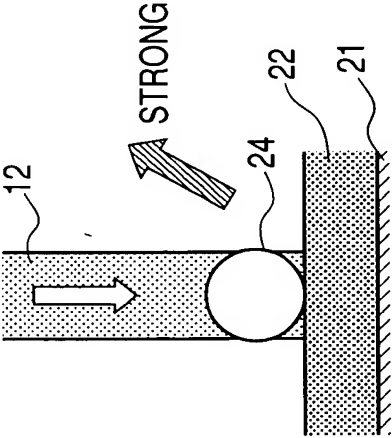
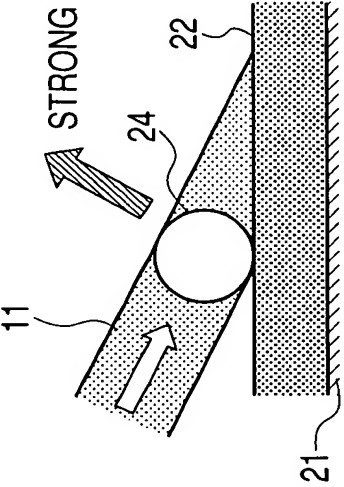
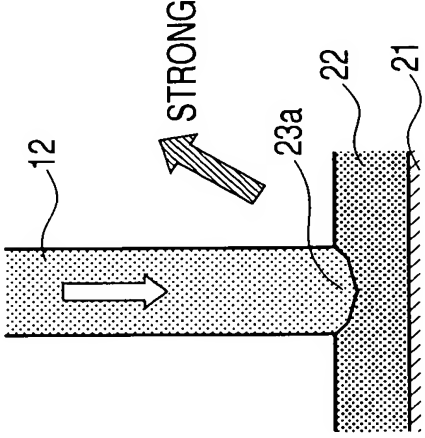
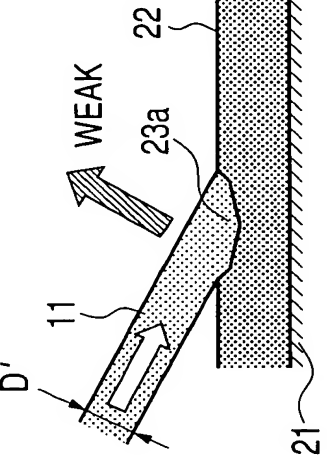
	INCIDENT ILLUMINATION	SLANTING ILLUMINATION
FOREIGN MATERIAL	 <p>A vertical rectangular block labeled 12 is shown on a horizontal surface labeled 21. A circular feature labeled 24 is on the top surface of the block. An arrow labeled 12 points upwards from the block. A hatched arrow labeled 'STRONG' points upwards and to the right, indicating the direction of incident illumination.</p>	 <p>The same vertical block 12 is shown on surface 21. A circular feature labeled 24 is on the top surface. An arrow labeled 11 points upwards and to the right, indicating the direction of slanting illumination. A hatched arrow labeled 'STRONG' points upwards and to the right, indicating the direction of slanting illumination.</p>
SCRATCH	 <p>A vertical rectangular block labeled 12 is shown on a horizontal surface labeled 21. A circular feature labeled 23a is on the top surface of the block. An arrow labeled 12 points upwards from the block. A hatched arrow labeled 'STRONG' points upwards and to the right, indicating the direction of incident illumination.</p>	 <p>The same vertical block 12 is shown on surface 21. A circular feature labeled 23a is on the top surface. An arrow labeled 11 points upwards and to the right, indicating the direction of slanting illumination. A hatched arrow labeled 'WEAK' points upwards and to the right, indicating the direction of slanting illumination. A dashed line labeled D' is shown on the surface 21.</p>

FIG. 5

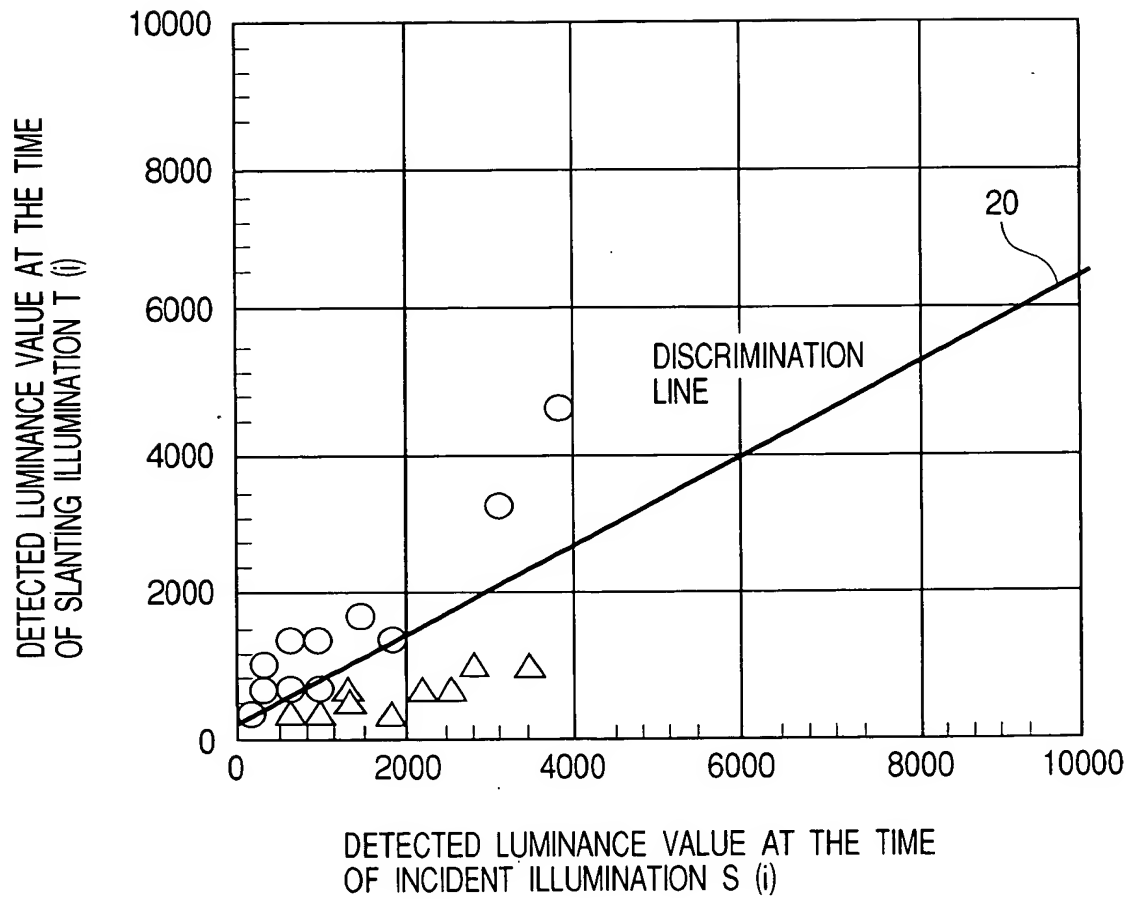


FIG. 6(a)

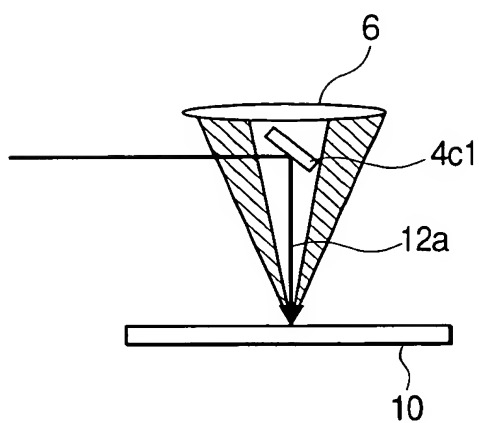


FIG. 6(b)

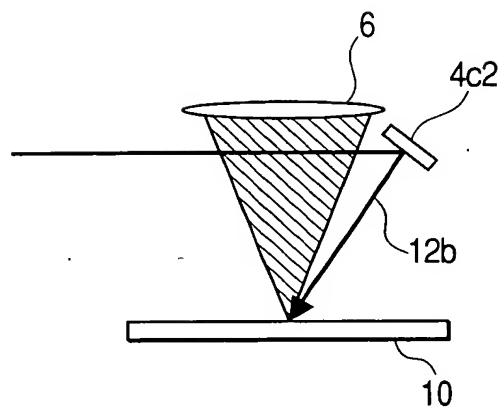


FIG. 6(c)

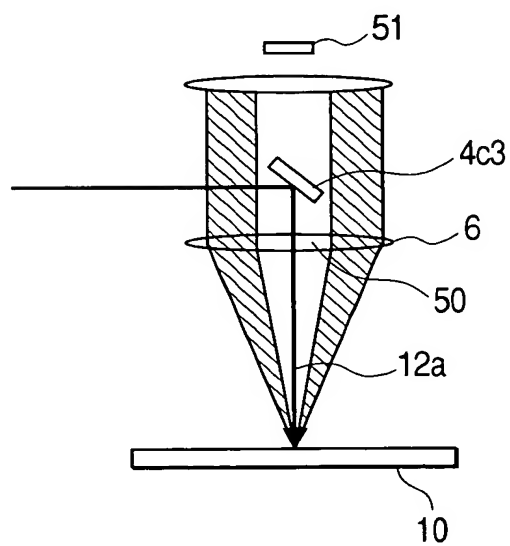


FIG. 6(d)

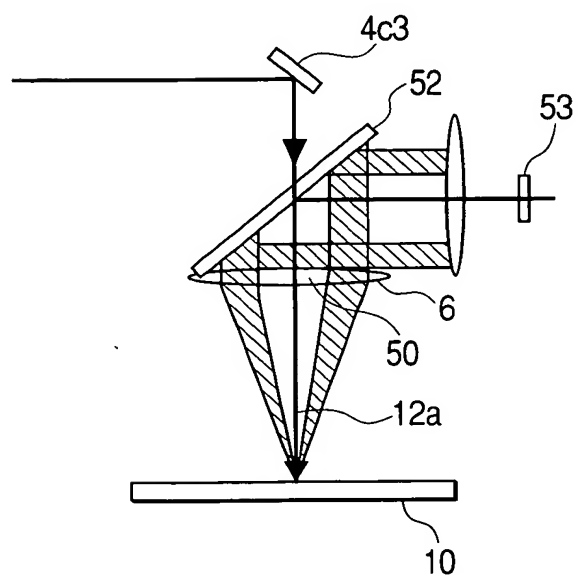


FIG. 7(a)

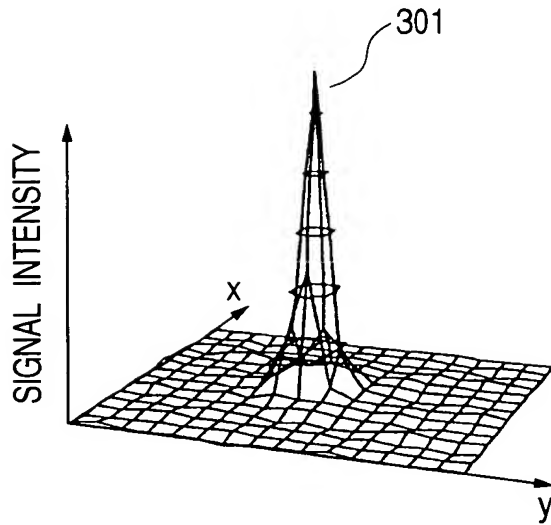


FIG. 7(b)

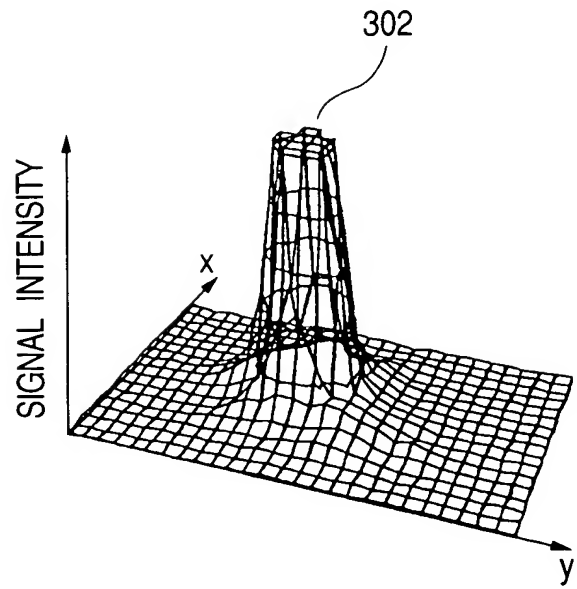
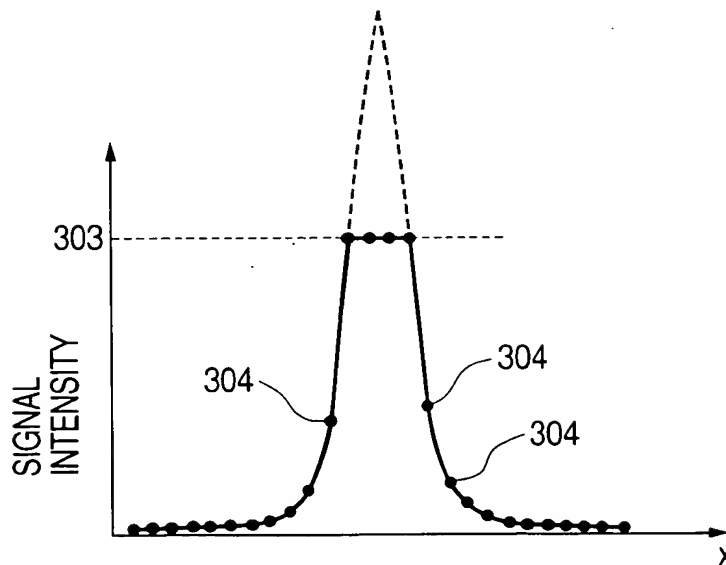


FIG. 7(c)



20250716-011300T

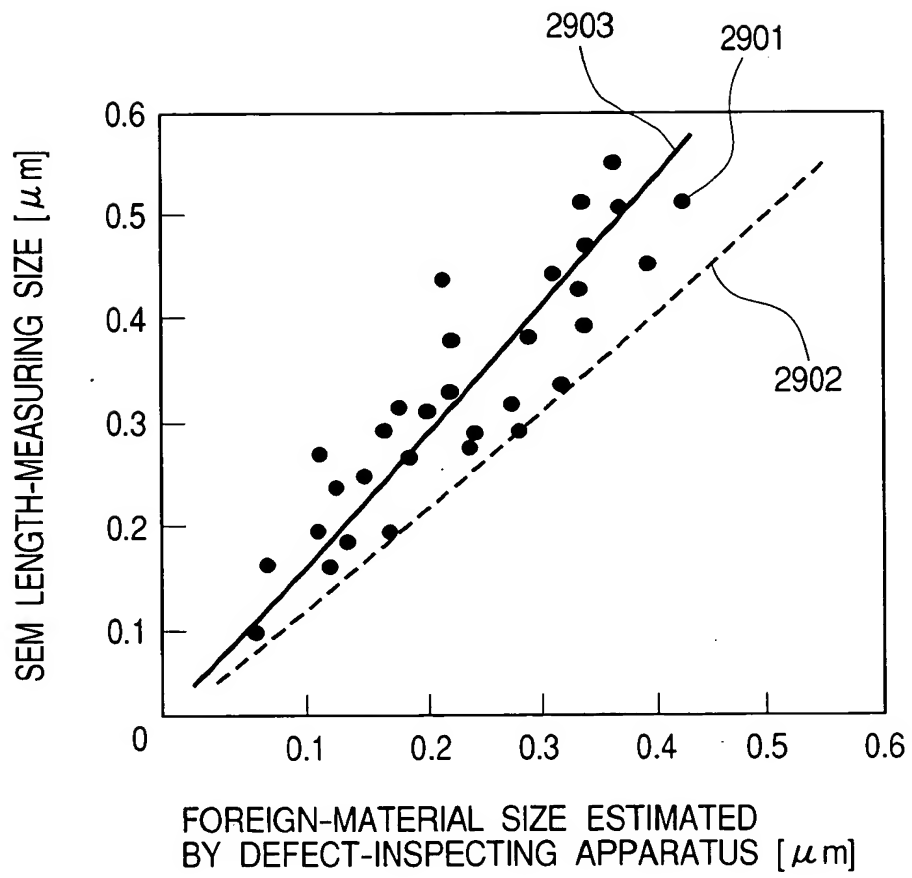
FIG. 8

FIG. 9(a)

FRONT-END PROCESS WAFER

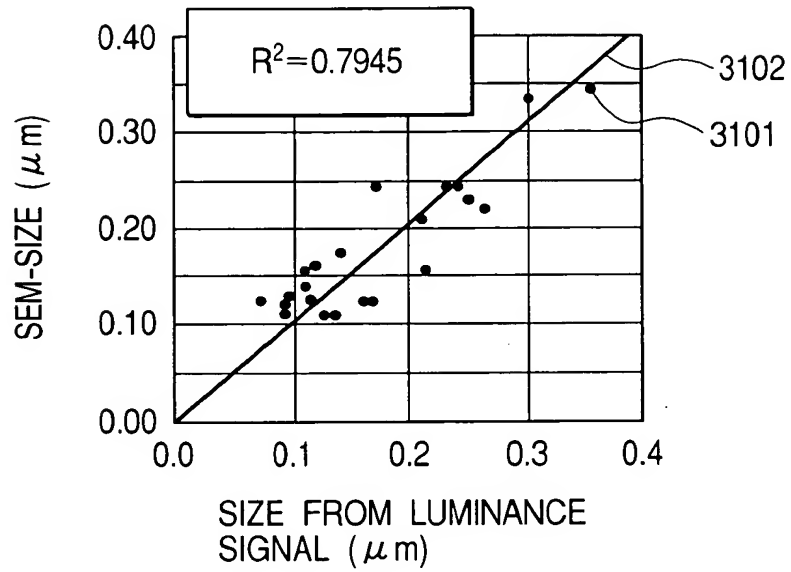


FIG. 9(b)

BACK-END PROCESS WAFER

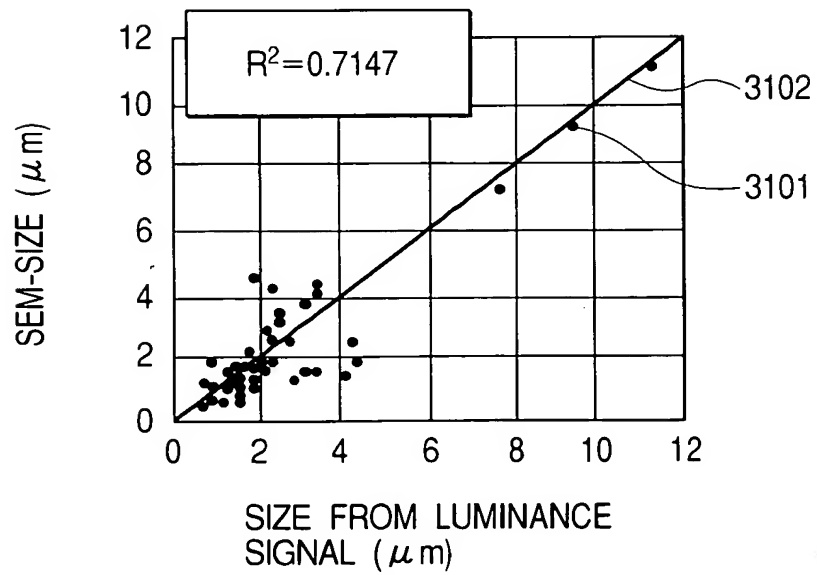


FIG. 10

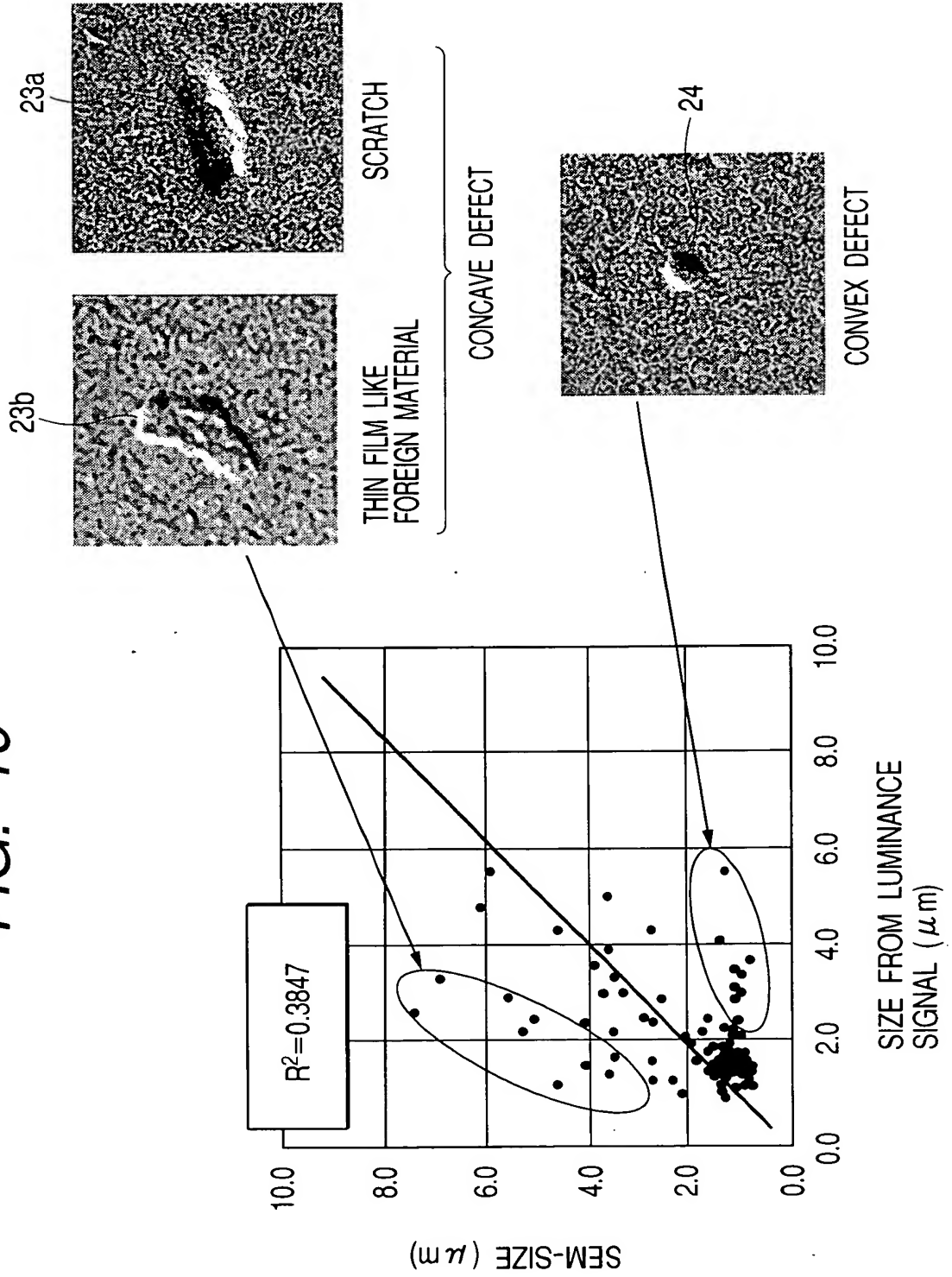


FIG. 11

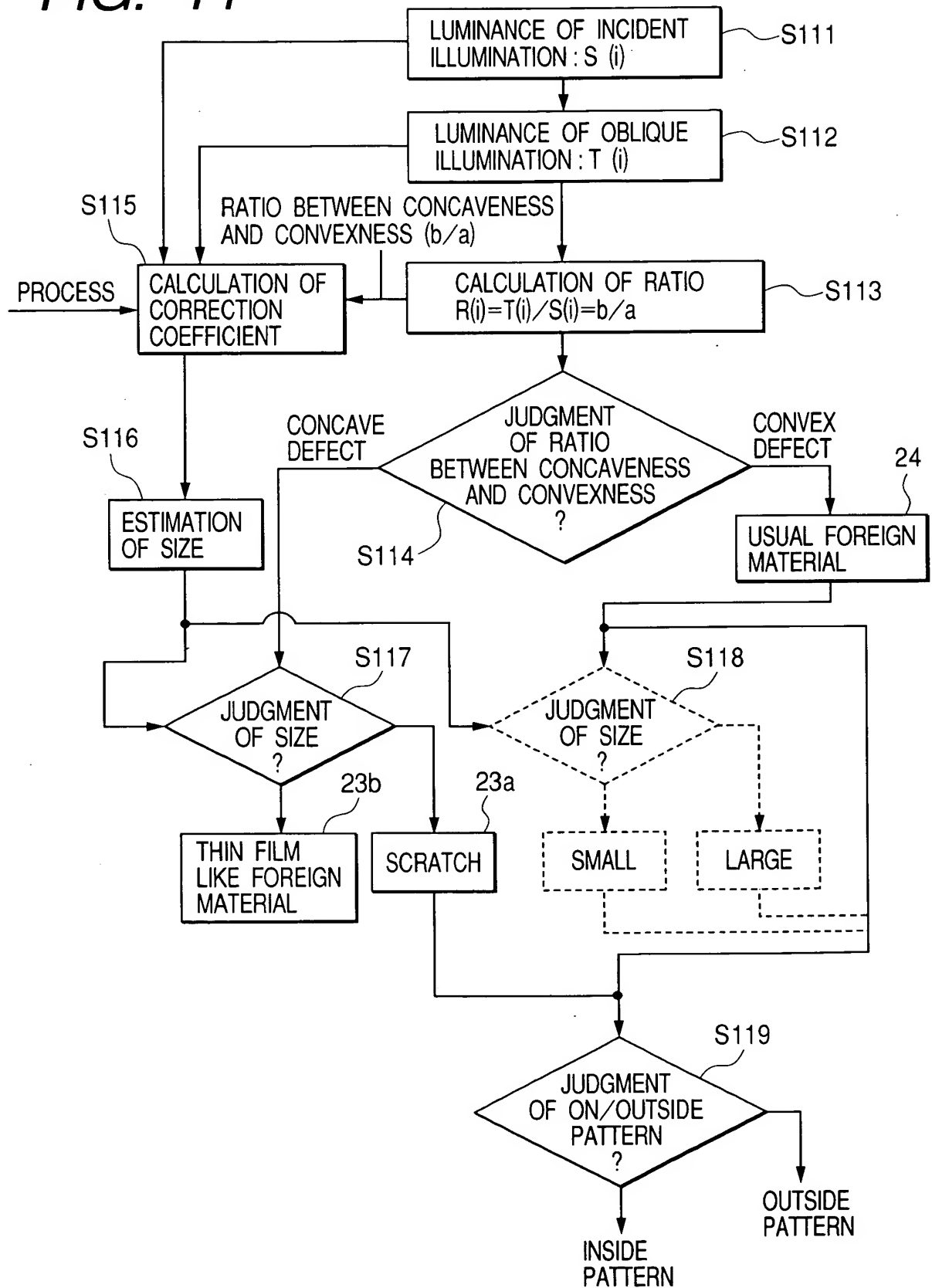


FIG. 12

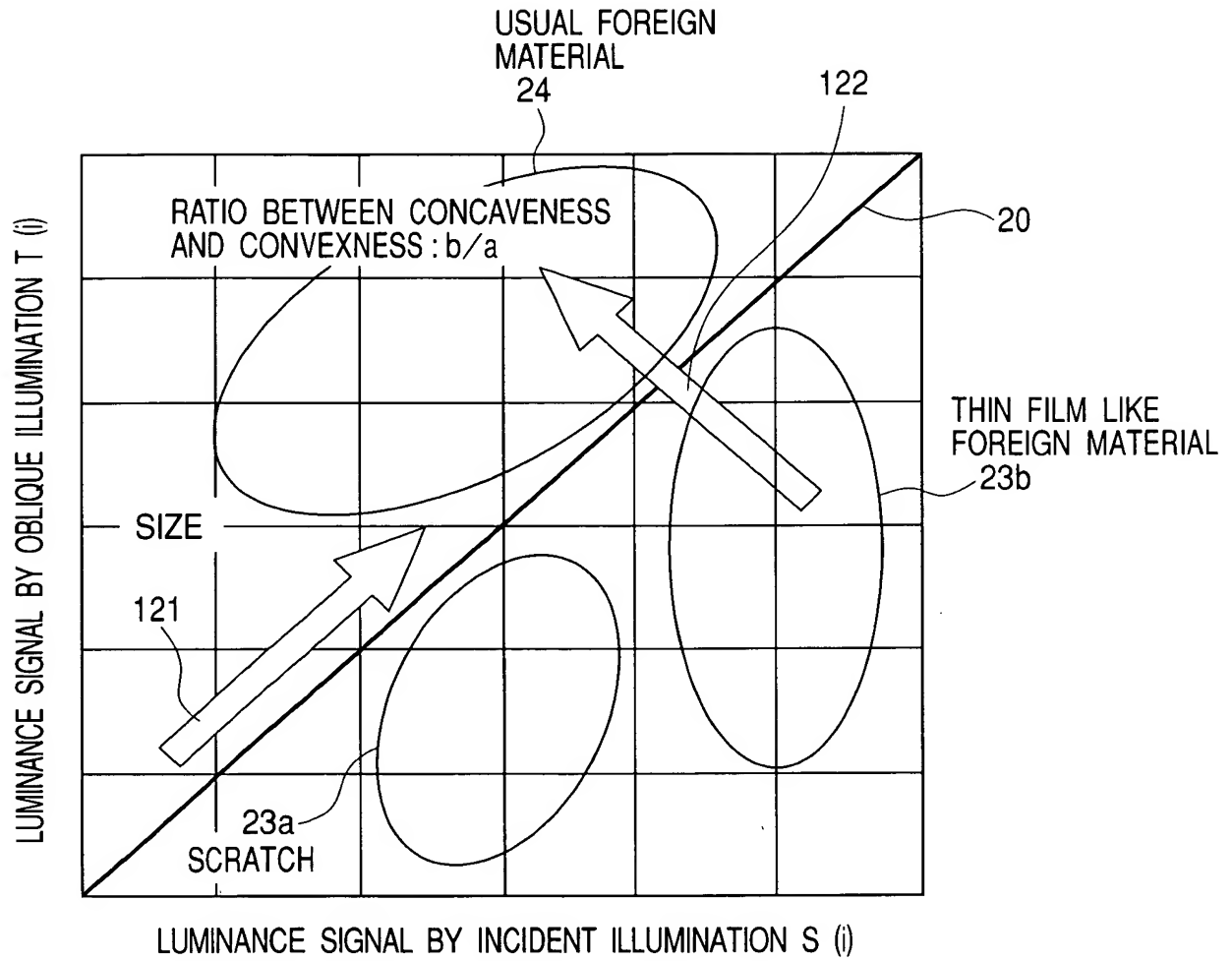


FIG. 13

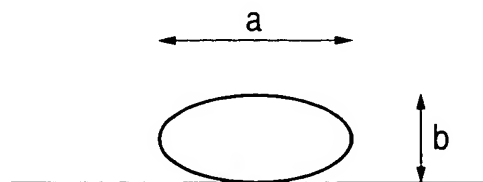


FIG. 14

SIZE	SMALL		LARGE
FOREIGN MATERIAL/ SCRATCH	FOREIGN MATERIAL	SCRATCH	———
ON PATTERN	CATEGORY 1	CATEGORY 3	CATEGORY 5
OUTSIDE PATTERN	CATEGORY 2	CATEGORY 4	

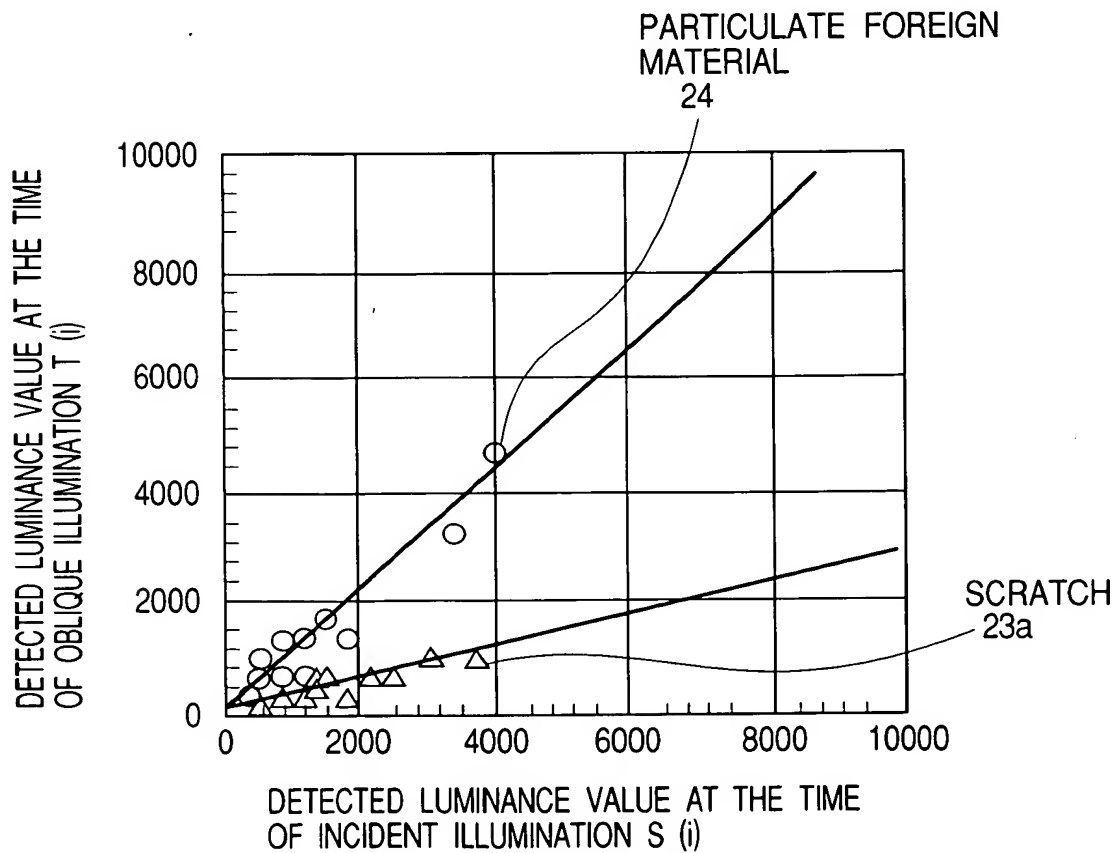
FIG. 15

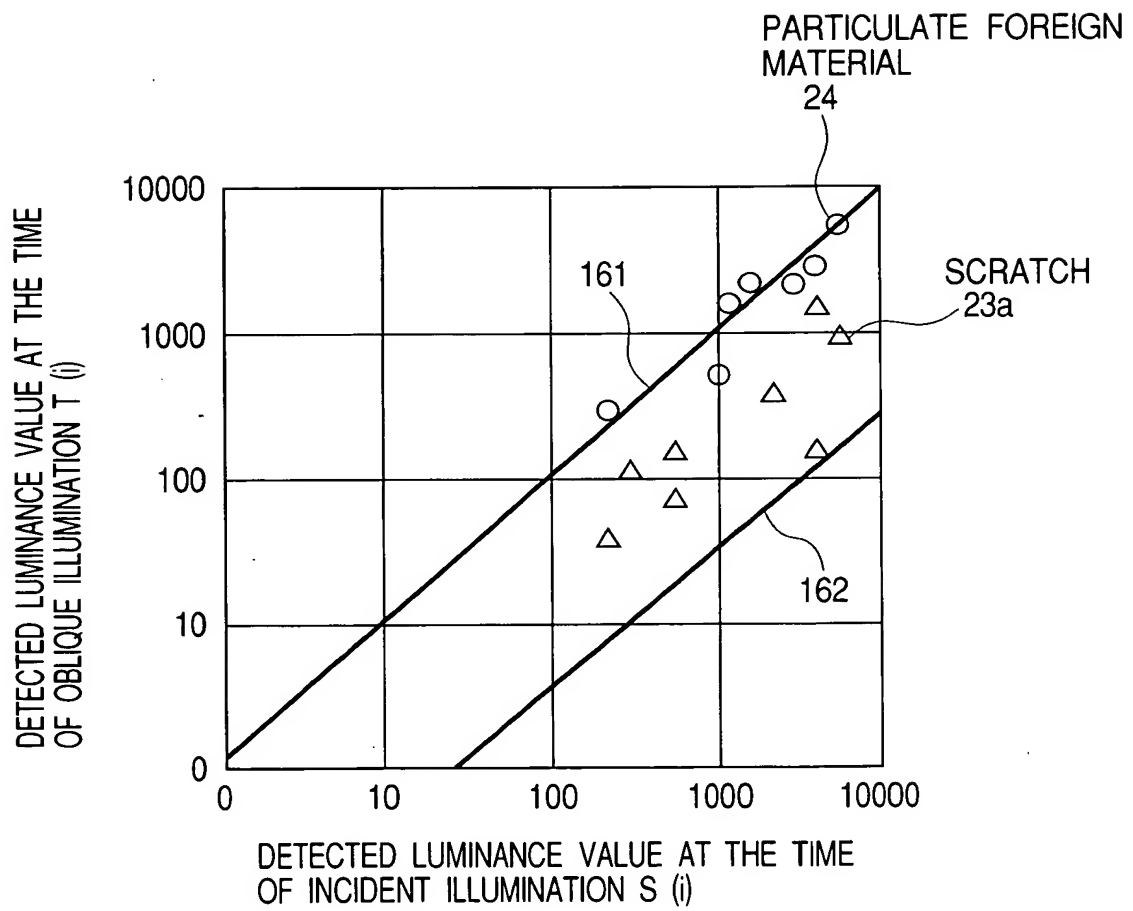
FIG. 16

FIG. 17(a)

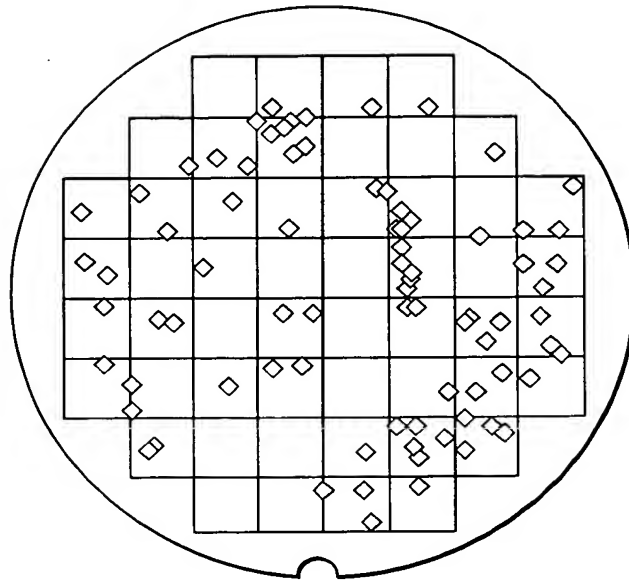


FIG. 17(b)

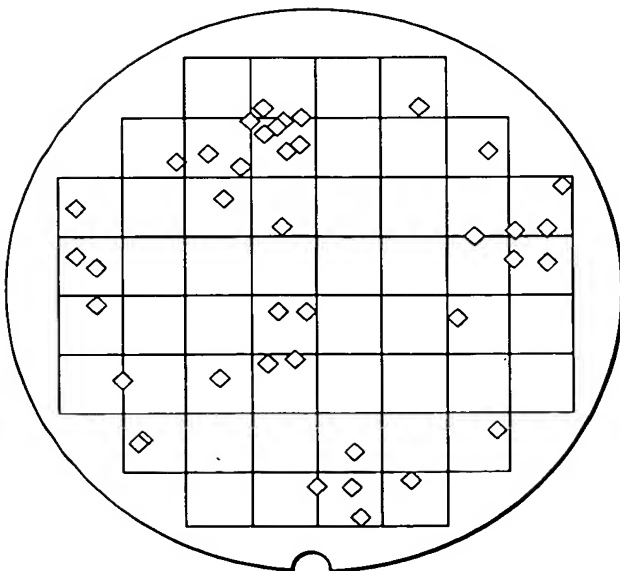


FIG. 17(c)

